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**UPDATE CHANGE NOTIFICATION # 20122**Generic Copy

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**Issue Date:** 23-Jul-2013

**TITLE:** Update Notice to FPCN 20122 - Capacity expansion for SOIC08 Copper Wire Products into ASE Kunshan, China

**PROPOSED FIRST SHIP DATE:** 04-Oct-2013

**AFFECTED CHANGE CATEGORY(S):** Subcontractor Assembly Site, Subcontractor Test Site

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[Shannon.Riggs@onsemi.com](mailto:Shannon.Riggs@onsemi.com)>

**NOTIFICATION TYPE:**

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

This update is issued to remove devices which were incorrectly listed on the original FPCN20122. The devices affected are TO-92 packages, and therefore not impacted by the intended capacity expansion.

**List of affected General Parts:**

The parts in table below are not affected by the change described in FPCN20122.

LM317LBZG

LM317LBZRAG

LM317LBZRPG